

Soldering Note of digital pressure sensor modules

Preface

Digital pressure sensor module is an electronic component sensitive to temperature. In order to ensure that you would not cause unnecessary damages or change the functions to them if possibly processing the modules, please follow the instruction to solder.

Solder Method

Hand solder is recommended instead of reflow solder.

The Selection of Soldering tools

According to both our soldering experiment and customers' feedback, we don't find that it results in obvious effect on soldering and products' functions by using open soldering pens (i.e. common soldering pens without closed-loop temperature control). However, considering the requirements of lead-free soldering and its productivity improvement, we suggest that you should use thermostatic soldering pen with closed-loop temperature control and select appropriate solder tip. Please kindly note that big solder tips, according to the feedback from customers, obviously bring about low efficiency of soldering and increase the possibility of short-circuit.

The Selection of Soldering Materials

——Sn96.5%/Ag3.0%/Cu0.5%

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The digital pressure sensor modules we provide are green products in complete accordance with the lead-free requirement; therefore, we suggest you should use environment-friendly lead-free soldering tin. We recommend two alloyed soldering tins as below to match the no-clean rosin (core and additive rosin):

——Sn96.5%/Ag3.0%/Cu0.5%

——Sn96.5%/Ag3.5%



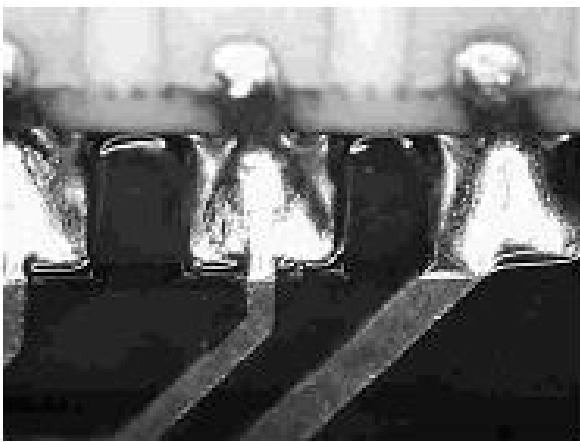
Soldering Conditions and Precautions

Please keep the practical soldering temperature under 260°C on the condition that you are able to control the temperature; otherwise, we suggest you should ensure the soldering temperature is less than 340°C.

In the course of soldering, please kindly note:

1. Arrange skilled operators to solder in order to shorten soldering time and lessen the fault rate.
2. When using additive rosin, please pay attention to the control of rosin to lessen or avoid rosin and tin splash.
3. The metal ring is protected with a film from the splash. Please check if the protected film is complete and in good condition.

Based on the actual situations, Customers are supposed to carry out soldering technics in line with the above-mentioned instructions. If you have any questions, please refer to our website or contact our technical staff.

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